

S/N: TBA

4/12/2001

DOCKET NO.: L/M-102-DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Steve M. Danziger, et al.

Serial No.: TO BE ASSIGNED
Divisional of 09/321,565

Art Unit: TO BE ASSIGNED

Filed: April 12, 2001

Examiner: TO BE ASSIGNED

For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects



TRANSMITTAL OF FORMAL DRAWINGS
UNDER 37 CFR §1.85

Assistant Commissioner of
Patents and Trademarks
Washington, D.C. 20231

BOX: DRAWING REVIEW BRANCH

Sir:

Attached for filing in the above-captioned matter are 6 (six)
sheets of formal drawings to be filed relative to the above
identified application.

Respectfully submitted,

Ronald R. Snider
Reg. No. 24,962

Date: April 12, 2001

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202T40-4822884

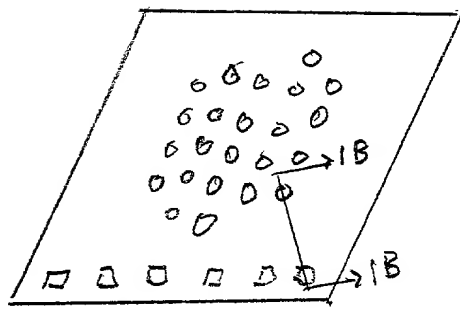


Fig 1A

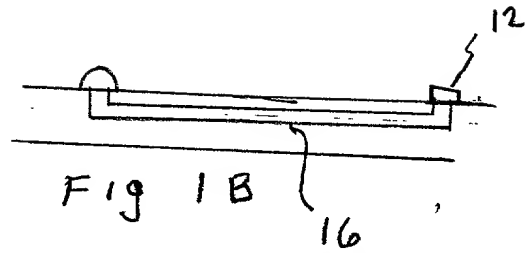


Fig 1B

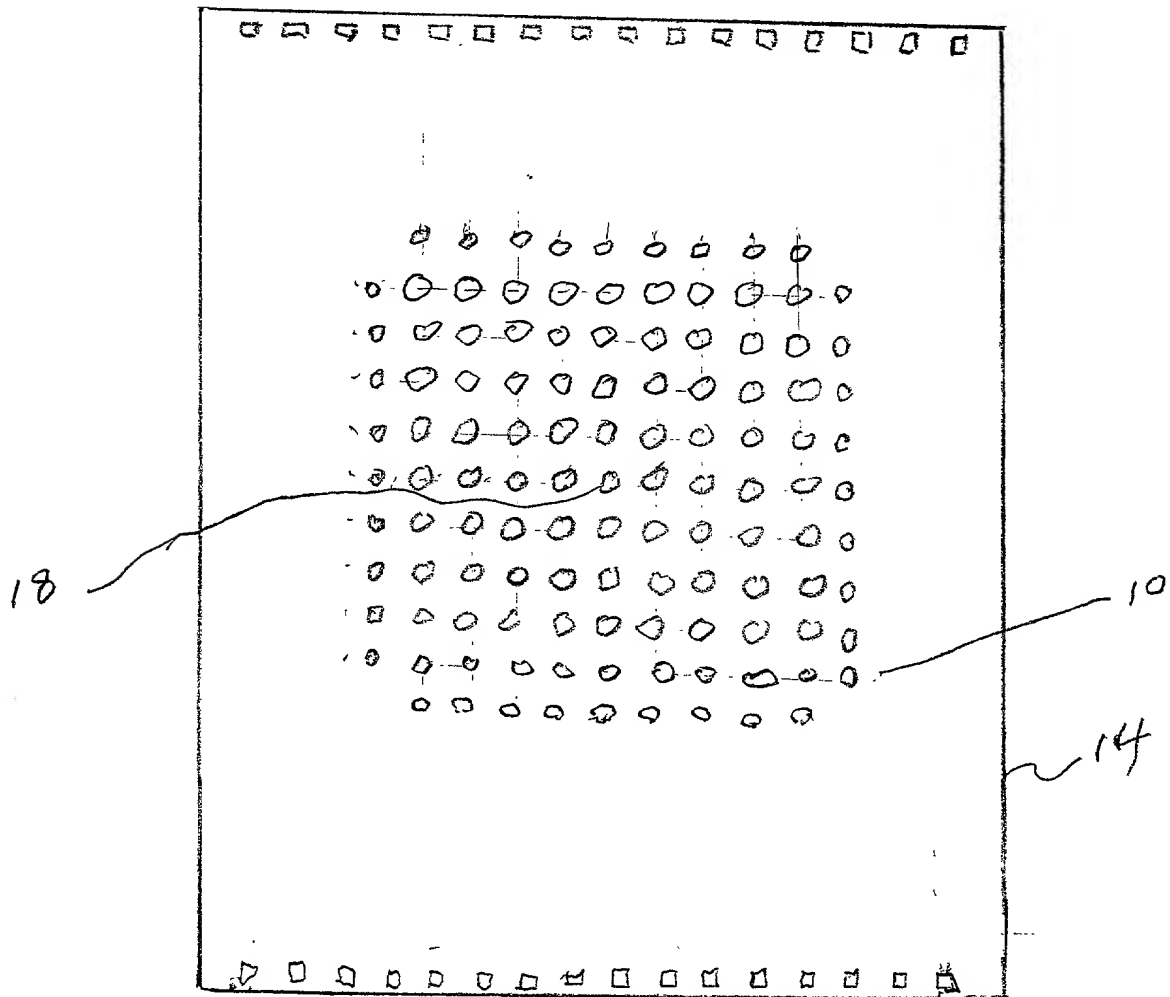


Fig 1

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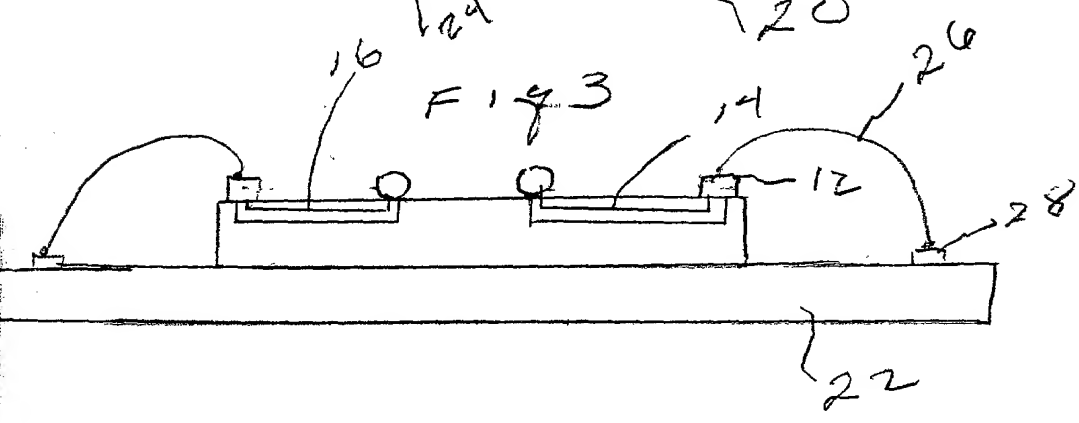
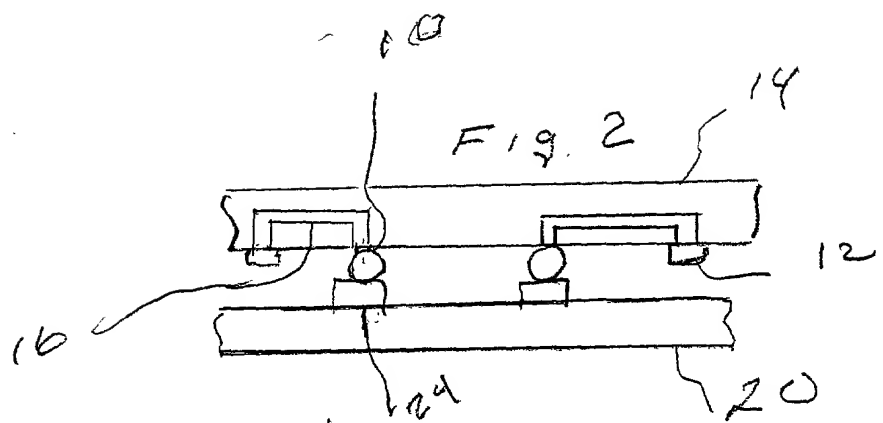


FIG. 2

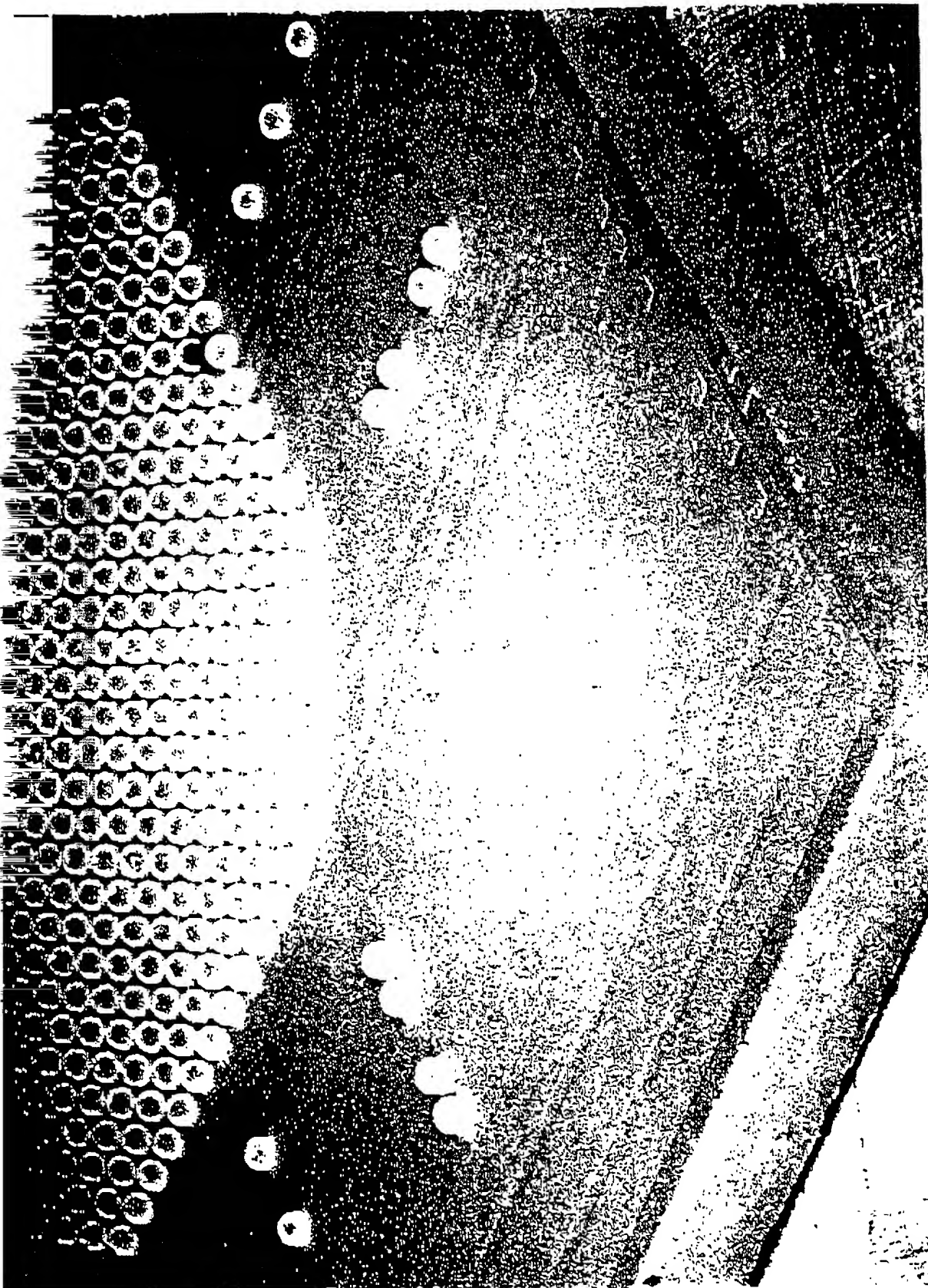
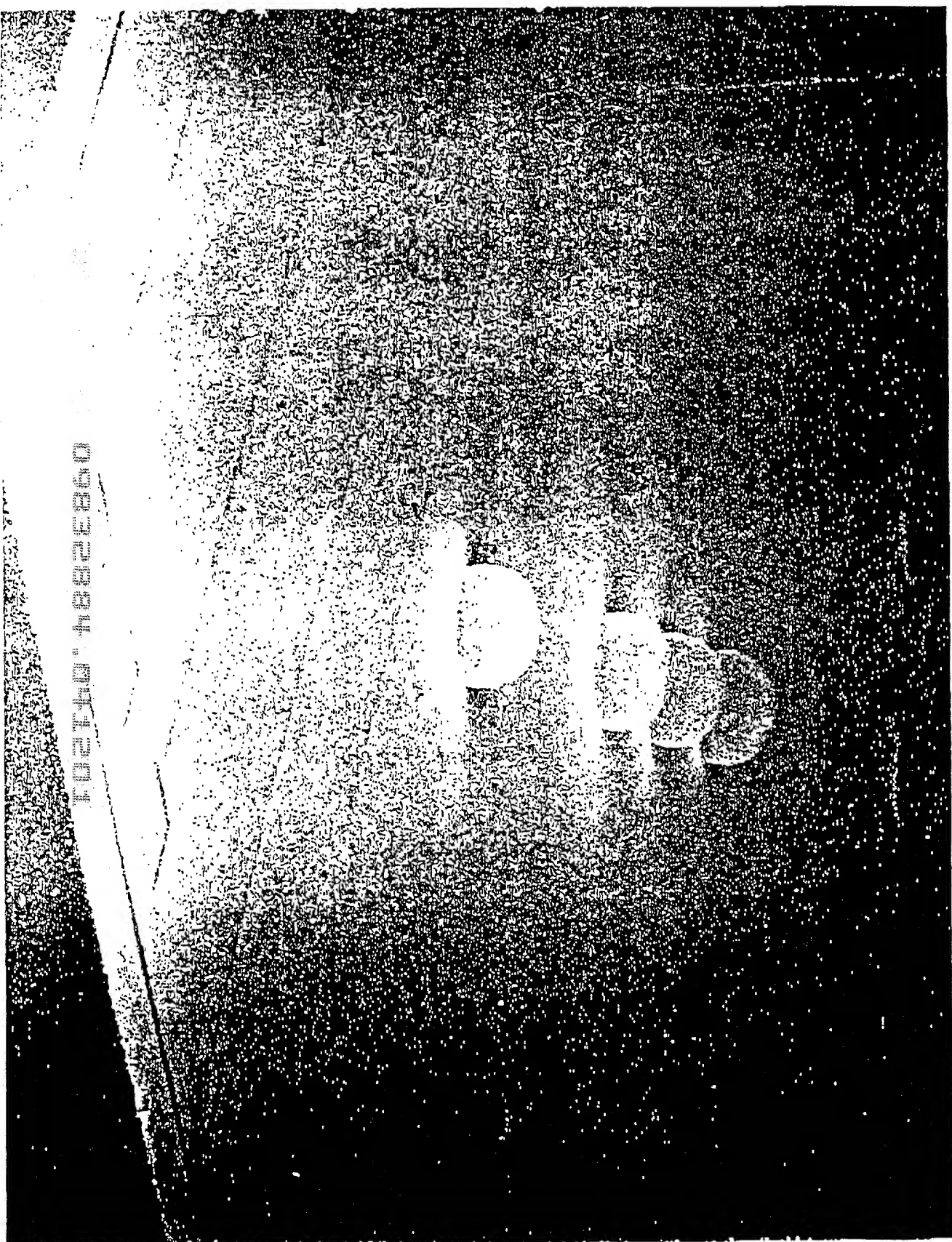


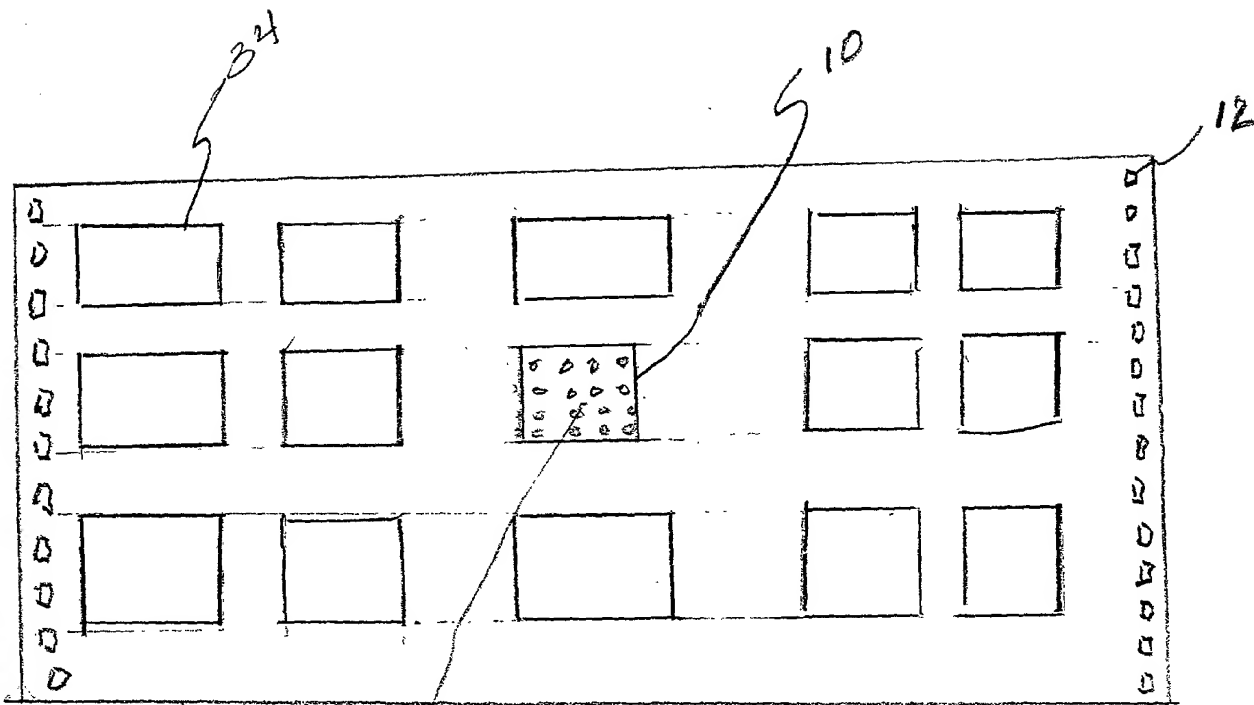
FIGURE 4

FIGURE 5



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TOP SECRET



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FIGURE 6